

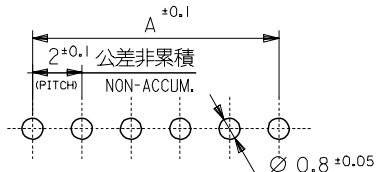
注記 NOTES

1. 嵌合相手: 51065 シリーズ
MATE WITH: 51065 SERIES
2. 材質 MATERIAL
ウエハー: 66ナイロン, UL94V-0
WAFER: 66NYLON, UL94V-0
ピン: 黄銅, 金メッキ
PIN: BRASS, GOLD (Au) PLATING
3. キングは下記表の位置及び形状に付加のこと。2極はキング無し。
KINK TO BE APPLIED AS FOLLOWS,
2 CIRCUIT HAS NO KINK.

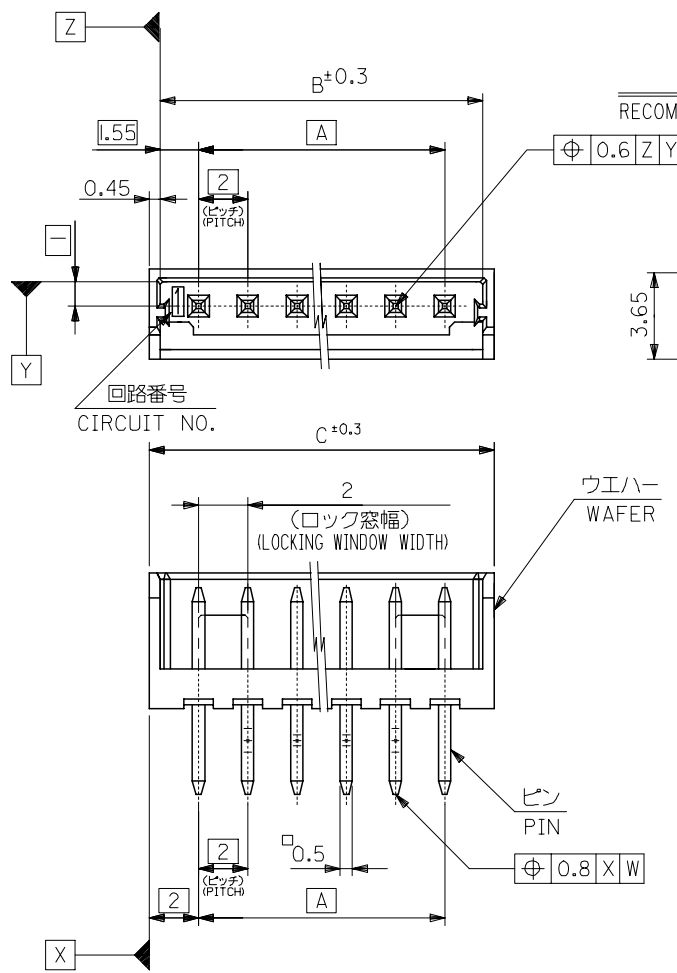
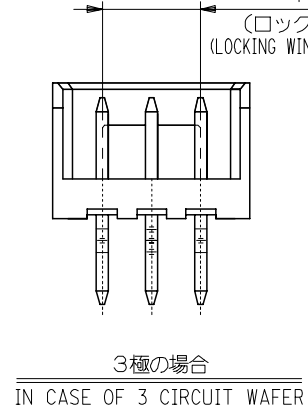
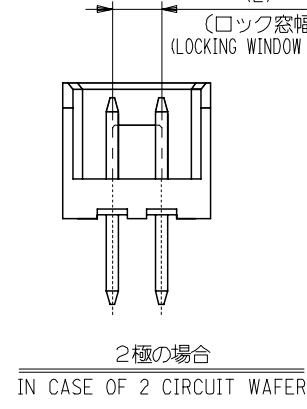
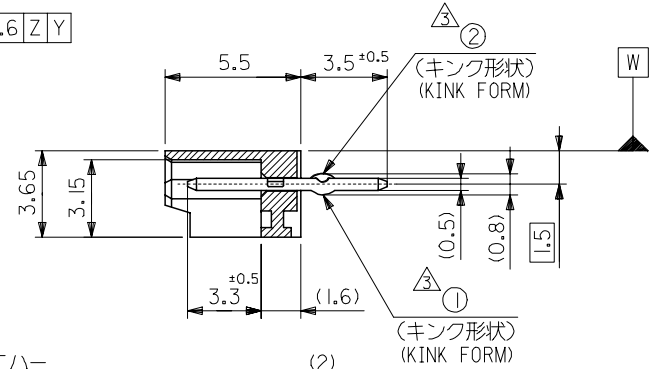
極数 CKT	回路番号 CKT NO.	回路番号							
		1	2	3	4	5	N-2	N-1	N
6 極以上	MORE THAN 6 CKT	—	①	②	—	—	②	①	—
5 極	5 CKT	①	②	—	②	①			
4 極	4 CKT	①	②	②	①				
3 極	3 CKT	①	②	①					

4. 本製品は、53253-**70の金メッキ品です。
THIS PRODUCT IS AU PLATING OF 53253-**70.
5. 梱包仕様 PACKAGING
502603-**70 トレー TRAY
502603-**50 ポリ袋 POLYBAG

32	31.1	28	502603-1550	502603-1570	15
30	29.1	26	-1450	-1470	14
28	27.1	24	-1350	-1370	13
26	25.1	22	-1250	-1270	12
24	23.1	20	-1150	-1170	11
22	21.1	18	-1050	-1070	10
20	19.1	16	-0950	-0970	9
18	17.1	14	-0850	-0870	8
16	15.1	12	-0750	-0770	7
14	13.1	10	-0650	-0670	6
12	11.1	8	-0550	-0570	5
10	9.1	6	-0450	-0470	4
8	7.1	4	-0350	-0370	3
6	5.1	2	502603-0250	502603-0270	2
C	B	A	MATERIAL NO.	MATERIAL NO.	極数
			MODEL NO.	MODEL NO.	



基板取付穴寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REFERENCE)



REV	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		10 UNDER	±0.2	MM ONLY	DATE			
0	RELEASED	10 OVER	±0.25	DATE	2007/03/30	5:1	METRIC	NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE-
	EC NO: J2007-2775	30 UNDER	±0.3	DATE	2007/03/30			MOLEX INCORPORATED
	DRWN: MAEDA	ANGULAR	±3 °	DATE	2007/03/30			SD-502603-001
	CHK: NUKITA	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DATE	2007/03/30			1 OF 1
	APPR: NUKITA	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DATE	2007/03/30			